

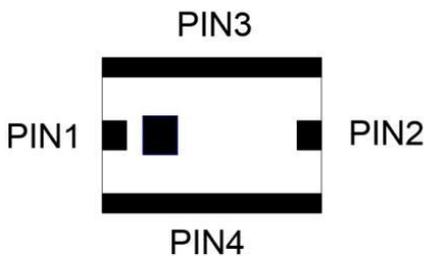
### Features

- Multilayer monolithic construction yields high reliability
- Low insertion loss and small size SMD chip design
- Can simplify your complex tuning and circuit design
- LTCC process

### Specifications

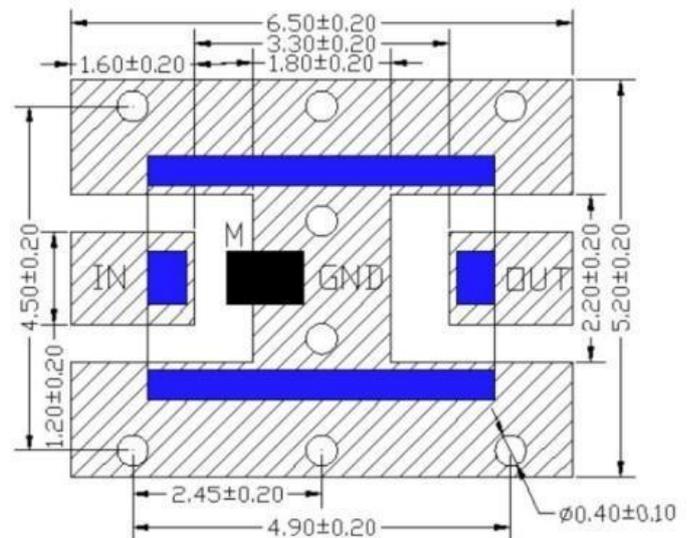
NO.	Parameter	Frequency	SPC	
			Min.	Max.
1	Insertion Loss (dB)	2000-2720 MHz		3.0
2	Attenuation (dB)	1640 MHz	25	
		3080 MHz	25	
3	VSWR	2000-2720 MHz		2.0
4	In/Output Impedance ( $\Omega$ )	50		
<b>Operating &amp; Storage Condition (Component)</b> Operation Temperature Range: $-40^{\circ}\text{C} \sim +85^{\circ}\text{C}$ Storage Temperature Range: $-40^{\circ}\text{C} \sim +85^{\circ}\text{C}$				
<b>Storage Condition before Soldering (Included packaging material)</b> Storage Temperature Range: $+5 \sim +40^{\circ}\text{C}$ Humidity: 30 to 70% relative humidity				

### Construction



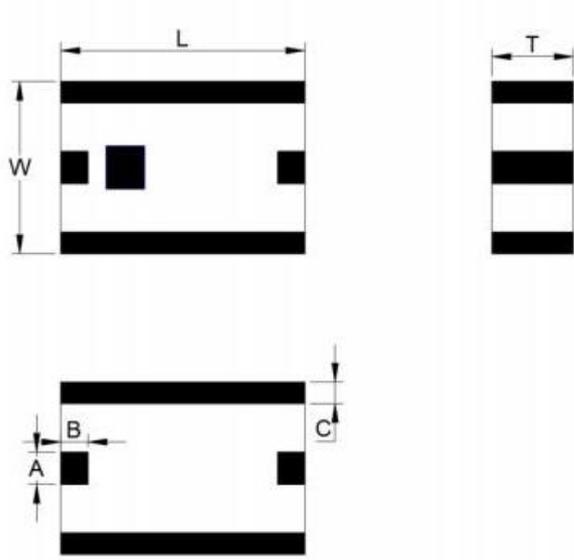
PIN	Connection
1	Input Port
2	Output Port
3	GND
4	GND

### Mounting Considerations

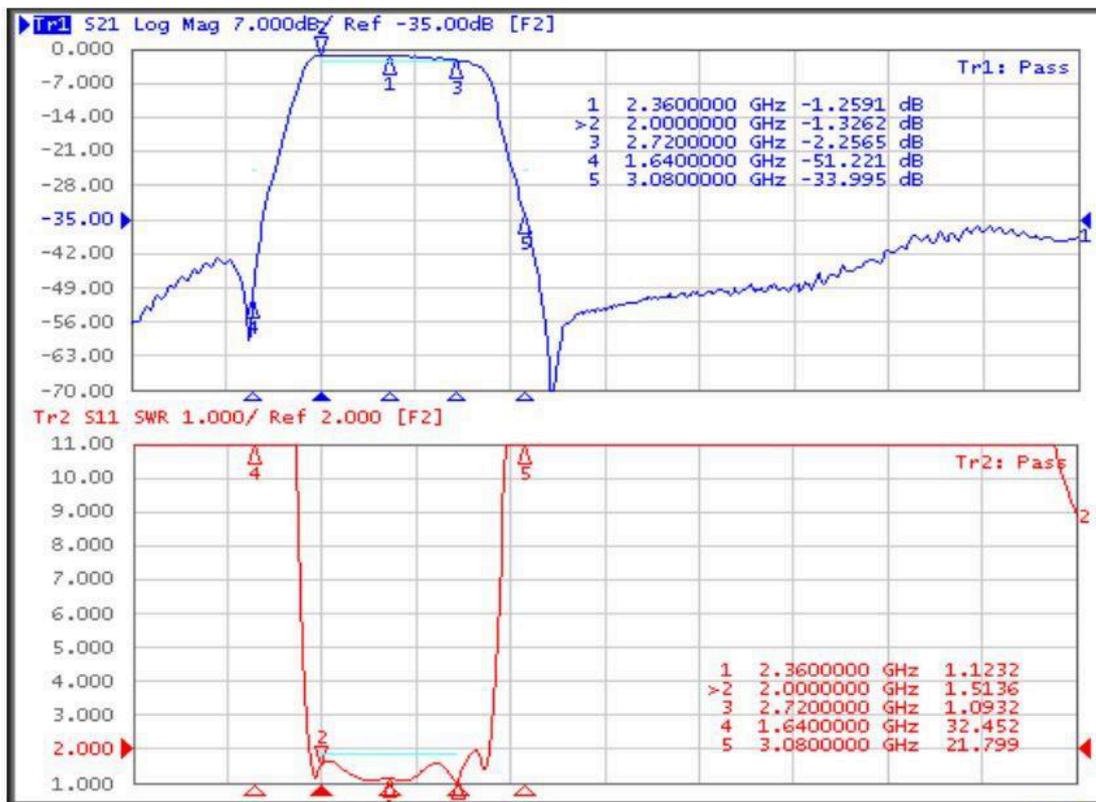


Unit: mm

### Dimensions

Figure	Symbol	Dimension (mm)
	L	4.5±0.20
	W	3.2±0.20
	T	1.5±0.20
	A	0.60±0.10
	B	0.50±0.10
	C	0.4±0.10

### Typical Electrical Characteristics (T=25°C)



### Solder Reflow Standard Conditioning



### Storage Conditions

Temperature : +5 to +30 °C

Humidity : 20 to 70% RH

Term of storage : Within 12 months (After the delivery) \*

Baking : Unnecessary

\* After peeling off cover tape, do not keep exposing the products to the open air. For the products stored longer than 12 months, confirm their terminals and solderability before use.